WHAT IS CLAIMED IS:

1. A liquid cooling system comprising:

a first electron conducting material including a first hot region and a first cold region capable of mating with a processor generating heat;

a second electron conducting material including a second hot region and a second cold region coupled to the first cold region, the second cold region capable of mating with the processor generating heat;

an inlet receiving cooled liquid;

a first conduit coupled to the inlet and coupled to the first hot region, the first conduit conveying the cooled liquid and dissipating heat from the first hot region in response to the cooled liquid;

a second conduit coupled to the inlet and coupled to the second hot region, the second conduit conveying the cooled liquid and dissipating heat from the second hot region in response to the cooled liquid; and

an outlet coupled to the first conduit and coupled to the second conduit, the outlet outputting heated liquid in response to the cooled liquid conveyed on the first conduit and in response to the cooled liquid conveyed on the second conduit liquid.

2. A liquid cooling system as set forth in claim 1, further comprising;

a third conduit coupled to the outlet, the third conduit transporting the heated liquid;

a heat exchange system coupled to the third conduit, the heat exchange system receiving the heated liquid transported on the third conduit and generating the cooled liquid; and

a fourth conduit coupled to the inlet and coupled to the heat exchange system, the inlet receiving the cooled liquid in response to transporting the cooled liquid on the fourth conduit.

3. A liquid cooling system as set forth in claim 2, wherein an input cavity is disposed in the heat exchange system, the input cavity receiving the heated liquid.

4. A liquid cooling system as set forth in claim 2, wherein a dissipater is disposed in the heat exchange system, the dissipater generating the cooled liquid in response to receiving the heated liquid.

5. A liquid cooling system as set forth in claim 2, wherein an output cavity is disposed in the heat exchange system, the output cavity receiving the cooled liquid.

6. A liquid cooling system as set forth in claim 5, wherein a pump is disposed in the output cavity, the pump pumping the cooled liquid, wherein the step of transporting the cooled liquid on the fourth conduit is performed in response to the pump pumping the cooled liquid.

7. A liquid cooling system as set forth in claim 1, wherein the liquid cooling system is disposed in a casing, the liquid cooling system further comprising a heat exchange system including a heat dissipater in liquid communication with the outlet;

a liquid cavity in liquid communication with the heat dissipater for storing the cooled liquid; and

a pump disposed within the liquid cavity for circulating the liquid through the liquid cooling system.

8. A liquid cooling system as set forth in claim 7, further comprising an airflow device for directing air from within the casing over the heat dissipater and out of the casing.

9. A liquid cooling system as set forth in claim 1, further comprising,

a third conduit coupled to the outlet, the third conduit transporting the heated liquid;

a heat exchange system coupled to the third conduit, the heat exchange system further comprising, a heat dissipater generating cooled liquid in response to receiving the heated liquid, a liquid cavity housing the cooled liquid, and a fan positioned between the heat dissipater and the liquid cavity, the fan causing air flow over the heat dissipater and the liquid cavity; and

a fourth conduit coupled to the inlet and coupled to the liquid cavity, the inlet receiving the cooled liquid in response to transporting the cooled liquid on the fourth conduit.

10. A liquid cooling system as set forth in claim 9, wherein the heat dissipater further comprises a liquid tube positioned within the heat dissipater, the liquid tube conveying the heated liquid through the heat dissipater to generate the cooled liquid.

11. A liquid cooling system as set forth in claim 9, further comprising a pump coupled to the liquid cavity, the pump enabling the step of transporting the cooled liquid on the fourth conduit.

12. A liquid cooling system comprising:

a heat transfer unit operating under the peltier effect, the heat transfer unit including a cold region and a hot region generating heat, wherein the cold region is capable of mating with a processor;

a conduit coupled to the hot region and dissipating heat by transporting cooled liquid, the cooled liquid transforming into heated liquid in response to receiving the heat from the hot region; and

a heat exchange unit coupled to the conduit and receiving the heated liquid, the heat exchange liquid generating the cooled liquid in response to receiving the heated liquid.

13. A liquid cooling system as set forth in claim 12, wherein the heat transfer unit comprises a first heat conducting material operating under the peltier effect and including a first hot region and a first cold region, a second heat conducting material operating under the peltier effect and including a second hot region and a second cold region, wherein the first hot region and the second hot region form the hot region and the first cold region and the second cold region form the cold region.

14. A liquid cooling system as set forth in claim 13, wherein the first conducting material and the second heat conducting material are coupled at a junction.

15. A liquid cooling system as set forth in claim 14, wherein the first heat conducting material and the second heat conducting material form a receptacle at the junction for mating with the processor.

16. A liquid cooling system comprising:

a first heat transfer unit operating under the peltier effect, the first heat transfer unit including a first cold region and a first hot region generating heat, wherein the first cold region is capable of mating with a processor on a first interface and dissipating heat from a first side; and

a second heat transfer unit operating under the peltier effect, the second heat transfer unit including a second cold region and a second hot region generating heat, wherein the second cold region is capable of mating with a processor on a second side and dissipating heat from the second side.

17. A liquid cooling system as set forth in claim 16, the liquid cooling system comprising:

a conduit coupled to the first hot region and dissipating heat by transporting cooled liquid, the cooled liquid transforming into heated liquid in response to receiving the heat from the first hot region; and

a heat exchange unit coupled to the conduit and receiving the heated liquid, the heat exchange liquid generating the cooled liquid in response to receiving the heated liquid.

18. A liquid cooling system as set forth in claim 16, the liquid cooling system comprising:

a conduit coupled to the second hot region and dissipating heat by transporting cooled liquid, the cooled liquid transforming into heated liquid in response to receiving the heat from the second hot region; and

a heat exchange unit coupled to the conduit and receiving the heated liquid the heat exchange liquid generating the cooled liquid in response to receiving the heated liquid.